



Pattern Recognition and Medical Data Analytics in Telemedicine

Guest Editors:

Dr. Rafal Doniec

rdoniec@polsl.pl

Prof. Dr. Marcin Grzegorzek

marcin.grzegorzek@uni-luebeck.de

Prof. Dr. Ewaryst Tkacz

etkacz@polsl.pl

Prof. Dr. Wojciech Glinkowski

wojciech.glinkowski@telemedycyna.org

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Message from the Guest Editors

Dear Colleagues,

Telemedicine is a rapidly evolving healthcare delivery mechanism via hardware and/or software through which consultation, medical assistance, and information can be communicated over the computer networks. During the COVID-19 pandemic, the importance of telemedicine increased. In this Special Issue, we would like to attract innovative and original research papers describing the latest research in the field of medical-based, engineering-based behavior. We also present a Special Issue to all those who wish to present their work in the area of health market management related to the use of sensor-based telemetry systems, using a wide range of artificial intelligence methods, including pattern recognition and machine learning algorithms. Potential topics include, but are not limited to:

- Artificial Intelligence;
- Cybersecurity processing of medical data;
- Medical Data Analytics;
- Future of Medical Data Analytics, Pattern Recognition and Telemedicine;
- Machine Learning, Deep learning in Telemedicine application;
- Pattern Recognition;
- Personalized healthcare;





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Editor-in-Chief

Prof. Dr. Takayoshi Kobayashi

Advanced Ultrafast Laser
Research Center, The University
of Electro-Communications, 1-5-
1, Chofugaoka, Chofu, Tokyo
182-8585, Japan

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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Contact Us

Applied Sciences
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

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